

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listings of Claims:

1. (original) An IC card comprising:

a semiconductor device having a semiconductor chip at least partially sealed with a first sealing portion made of a thermosetting resin material and having, over a first surface, an external connection terminal electrically connected to the semiconductor chip;

a case which is made of a thermoplastic resin material and to which the semiconductor device is to be loaded; and

a second sealing portion which is made of a thermoplastic resin material and seals the semiconductor device so as to expose the external connection terminal, thereby integrating the semiconductor device with the case.

2. (original) An IC card according to Claim 1,

wherein the semiconductor device comprises:

a wiring substrate having the external connection terminal and an interconnect:

the semiconductor chip disposed over the wiring substrate and electrically connected to the external connection terminal via the interconnect: and

the first sealing portion made of a thermosetting resin material and formed over the wiring substrate so as to seal the semiconductor chip at least partially.

3. (original) An IC card according to Claim 2, wherein the first sealing portion is formed to cover the semiconductor chip.

4. (original) An IC card according to Claim 2, wherein the semiconductor device has a connecting member for electrically connecting the interconnect of the wiring substrate with the semiconductor chip, and the first sealing portion covers the connecting member.

5. (original) An IC card according to Claim 2, wherein the semiconductor chip is disposed over a surface of the wiring substrate on a side opposite to a surface over which the external connection terminal is formed.

6. (original) An IC card according to Claim 1, wherein the second sealing portion is formed to cover a

region, other than the external connection terminal, of the first surface of the semiconductor device.

7. (original) An IC card according to Claim 1, wherein the case and the second sealing portion are made of the same material.

8. (original) An IC card according to Claim 1, wherein the second sealing portion is welded with the interface portion of the case.

9. (original) An IC card according to Claim 1, wherein a projecting portion is formed over the first surface of the semiconductor device, the external connection terminal is formed over the projecting portion of the first surface, and the second sealing portion is formed to cover a region, other than the projecting portion, of the first surface of the semiconductor device.

10. (original) An IC card according to Claim 1, wherein the first sealing portion is made of an epoxy resin containing a silica filler.

11. (original) An IC card according to Claim 1, wherein the semiconductor device comprises:

a die pad portion;
the semiconductor chip disposed over the die pad
portion;
a lead portion electrically connected to the
semiconductor chip; and
the first sealing portion covering the die pad
portion, the semiconductor chip and the lead portion and
exposing, as the external connection terminal, a part of
the lead portion from the outer surface of the first
sealing portion.

Claims 12-24 (canceled)